IN THE CLAIMS

Please cancel Claim 1 without prejudice or disclaimer.

Claim 1 (cancelled).

Claim 2 (currently amended):   The insulation film according to claim ~~1~~ 3 wherein the pitch L and the pitch p satisfy the following equation: m p = n L wherein n and m are integers that satisfy the equation n < m.

Claim 3 (currently amended):   An insulation film for providing an insulation substrate for carrying a semiconductor chip of a semiconductor package comprising:
two rows of sprocket holes comprising a plurality of sprocket holes formed at a pitch L along both edges of the insulation film;
a plurality of through holes is formed two-dimensionally at a pitch p between the rows of sprocket holes; and
the plurality of through holes for use selectively as through holes for the insulation substrate of the semiconductor package according to size of the semiconductor package.
~~The insulation film according to claim 1~~ wherein the insulation film comprises:
a plurality of circuit patterns formed two-dimensionally upon the insulation film according to size of the semiconductor package; and
a for-plating-electricity-supply-use conductor pattern electrically connected with the plurality of circuit patterns.

Claim 4 (original): The insulation film according to claim 3 wherein the for-plating-electricity-supply-use conductor pattern comprises:
a main line surrounding a perimeter of the plurality of circuit patterns; and
a sub-line electrically connecting each of the circuit patterns to the main line.